ELECTRICAL CHARACTERISTICS (Ambient Temperature = 25°C unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward Voltage	V_F	I_F = 10mA	1.0	1.15	1.3	V
Reverse Voltage	V_R	I_R = 10µA	5.0			V
Reverse Leakage	I_R	V_R = 5V			10	µA
Terminal Capacitance	C_t	V = 0V, f = 1KHz		30	250	pF

OUTPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Collector—Emitter breakdown Voltage	BV_{CEO}	I_C = 0.5mA, I_F = 0mA	55			V
Emitter—Collector breakdown Voltage	BV_{ECO}	I_E = 100µA, I_F = 0mA	6			V
Collector-Emitter Dark Current	I_{CEO}	V_{CE} = 24V, I_F = 0mA			100	nA

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ELECTRICAL CHARACTERISTICS (Ambient Temperature = 25°C unless otherwise specified)

COUPLED

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Current Transfer Ratio	CTR	I_F = 5mA, V_{CE} = 5V	50		600	%
		Optional CTR Grades				
		GR	100		300	
		BL	200		600	
		GB	100		600	
		GB (I_F = 1mA, V_{CE} = 0.4V)	30			
Collector—Emitter Saturation Voltage	$V_{CE(sat)}$	I_F = 8mA, I_C = 2.4mA GB (I_F = 1mA, I_C = 0.2mA)			0.4 0.4	V
Output Rise Time	t_r	V_{CE} = 10V, Ic = 2mA, R_L = 100Ω		2		µs
Output Fall Time	t_f			3		
Turn-on Time	t_{on}			3		
Turn-off Time	t_{off}			3		

ISOLATION

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Input to Output Isolation Voltage	V_{ISO}	AC 1 minute, RH = 40 to 60% Note 1	5300			V_{RMS}
Input to Output Isolation Resistance	R_{ISO}	V_{IO}= 500V Note 1	$5x10^{10}$			Ω

Note 1 : Measure with input leads shorted together and output leads shorted together.

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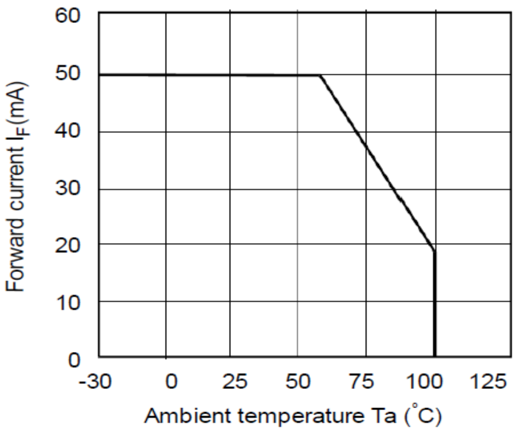

Fig 1 Forward Current vs T_A

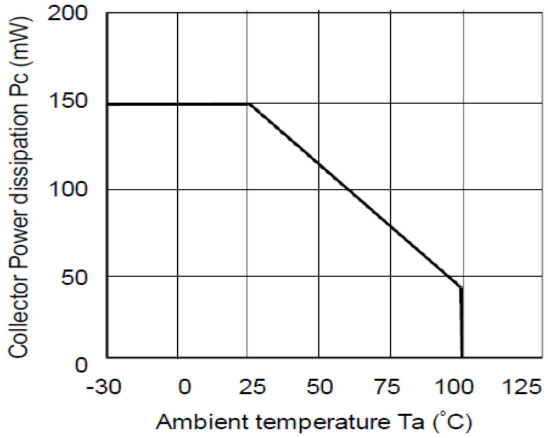

Fig 2 Collector Power Dissipation vs T_A

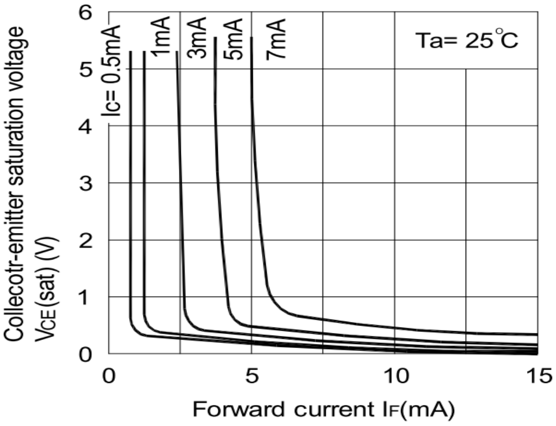

Fig 3 Collector-emitter Saturation Voltage vs Forward Current

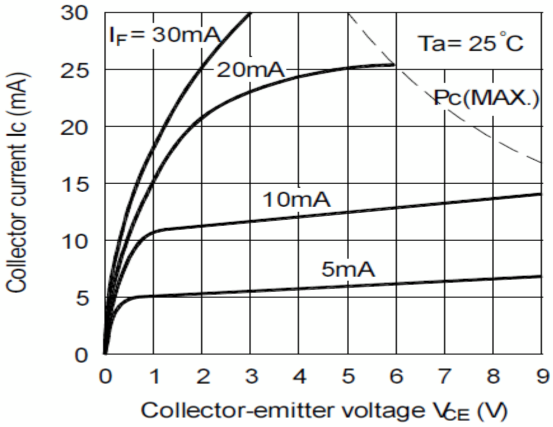

Fig 4 Collector Current vs Collector-emitter Voltage

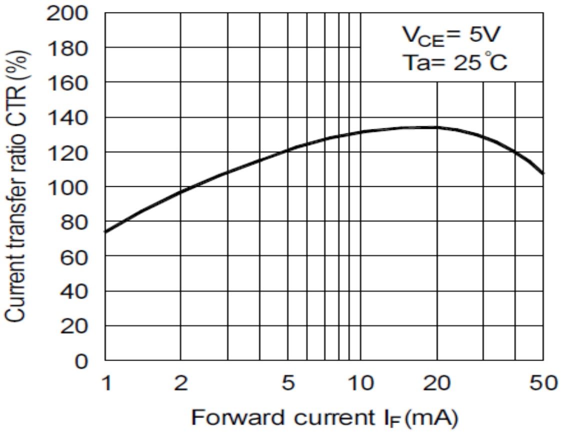

Fig 5 Current Transfer Ratio vs Forward Current

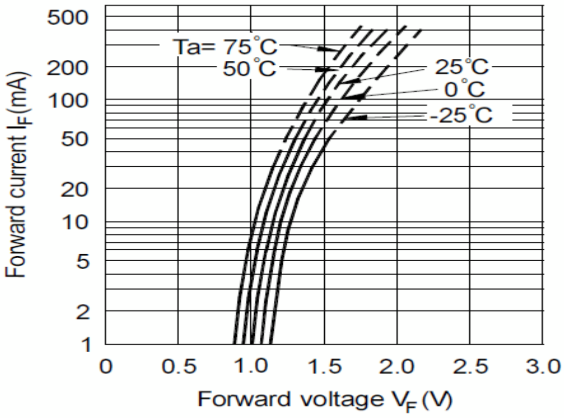

Fig 6 Forward Current vs Forward Voltage

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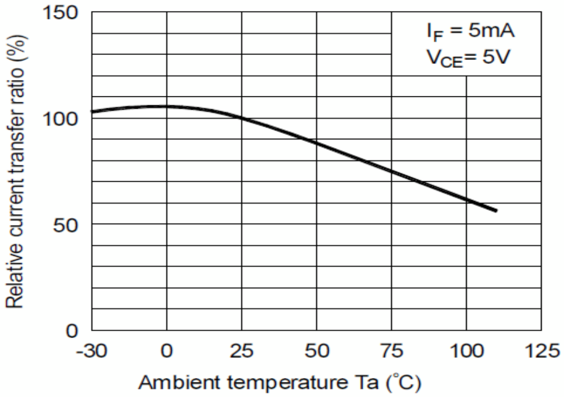


Fig 7 Relative CTR vs T_A

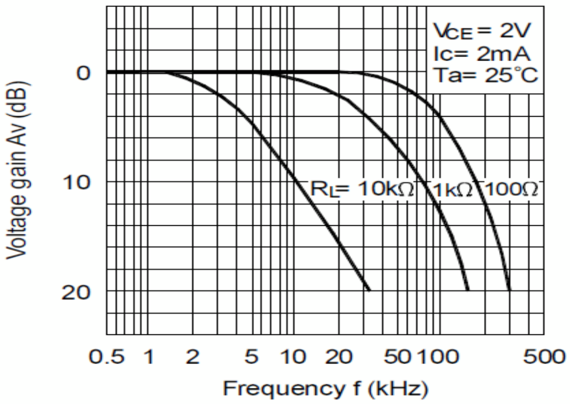


Fig 8 Frequency Response

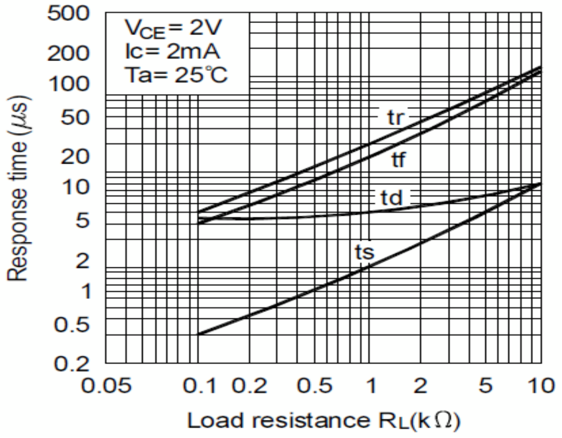
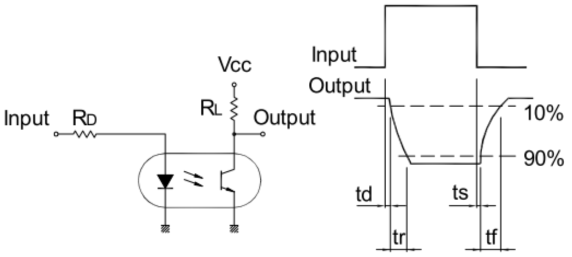


Fig 9 Response Time vs Load Resistance



Response Time Test Circuit

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ORDER INFORMATION

TLP621 (UL Approval)

After PN	PN	Description	Packing quantity
None	TLP621, TLP621GR, TLP621BL, TLP621GB	Standard DIP4	100 pcs per tube
G	TLP621G, TLP621GRG, TLP621BLG, TLP621GBG	10mm Lead Spacing	100 pcs per tube
SM	TLP621SM, TLP621GRSM, TLP621BLSM, TLP621GBSM	Surface Mount	100 pcs per tube
SMT&R	TLP621SMT&R, TLP621GRSMT&R, TLP621BLSMT&R, TLP621GBSMT&R	Surface Mount Tape & Reel	1000 pcs per reel

TLP621-2 (UL Approval)

After PN	PN	Description	Packing quantity
None	TLP621-2, TLP621-2GR, TLP621-2BL, TLP621-2GB	Standard DIP8	50 pcs per tube
G	TLP621-2G, TLP621-2GRG, TLP621-2BLG, TLP621-2GBG	10mm Lead Spacing	50 pcs per tube
SM	TLP621-2SM, TLP621-2GRSM, TLP621-2BLSM, TLP621-2GBSM	Surface Mount	50 pcs per tube
SMT&R	TLP621-2SMT&R, TLP621-2GRSMT&R, TLP621-2BLSMT&R, TLP621-2GBSMT&R	Surface Mount Tape & Reel	1000 pcs per reel

TLP621-4 (UL Approval)

After PN	PN	Description	Packing quantity
None	TLP621-4,TLP621-4GR, TLP621-4BL, TLP621-4GB	Standard DIP16	25 pcs per tube
G	TLP621-4G, TLP621-4GRG, TLP621-4BLG, TLP621-4GBG	10mm Lead Spacing	25 pcs per tube
SM	TLP621-4SM, TLP621-4GRSM, TLP621-4BLSM, TLP621-4GBSM	Surface Mount	25 pcs per tube

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TLP621, TLP621-2, TLP621-4

ORDER INFORMATION

TLP621X (UL and VDE Approvals)			
After PN	**PN**	**Description**	**Packing quantity**
None	TLP621X, TLP621XGR, TLP621XBL, TLP621XGB	Standard DIP4	100 pcs per tube
G	TLP621XG, TLP621XGRG, TLP621XBLG, TLP621XGBG	10mm Lead Spacing	100 pcs per tube
SM	TLP621XSM, TLP621XGRSM, TLP621XBLSM, TLP621XGBSM	Surface Mount	100 pcs per tube
SMT&R	TLP621XSMT&R, TLP621XGRSMT&R, TLP621XBLSMT&R, TLP621XGBXSMT&R	Surface Mount Tape & Reel	1000 pcs per reel

TLP621-2X (UL and VDE Approvals)			
After PN	**PN**	**Description**	**Packing quantity**
None	TLP621-2X, TLP621-2XGR, TLP621-2XBL, TLP621-2XGB	Standard DIP8	50 pcs per tube
G	TLP621-2XG, TLP621-2XGRG, TLP621-2XBLG, TLP621-2XGBG	10mm Lead Spacing	50 pcs per tube
SM	TLP621-2XSM, TLP621-2XGRSM, TLP621-2XBLSM, TLP621-2XGBSM	Surface Mount	50 pcs per tube
SMT&R	TLP621-2XSMT&R, TLP621-2XGRSMT&R, TLP621-2XBLSMT&R, TLP621-2XGBSMT&R	Surface Mount Tape & Reel	1000 pcs per reel

TLP621-4X (UL and VDE Approvals)			
After PN	**PN**	**Description**	**Packing quantity**
None	TLP621-4X, TLP621-4XGR, TLP621-4XBL, TLP621-4XGB	Standard DIP16	25 pcs per tube
G	TLP621-4XG, TLP621-4XGRG, TLP621-4XBLG, TLP621-4XGBG	10mm Lead Spacing	25 pcs per tube
SM	TLP621-4XSM, TLP621-4XGRSM, TLP621-4XBLSM, TLP621-4XGBSM	Surface Mount	25 pcs per tube

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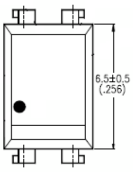
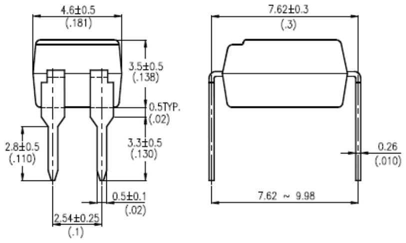
PACKAGE DIMENSIONS in mm (inch)

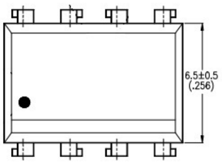
DIP

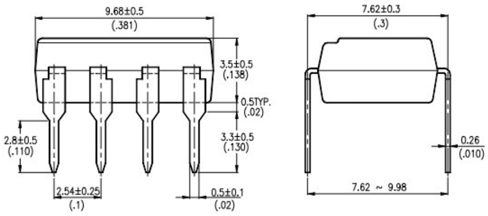
TLP621



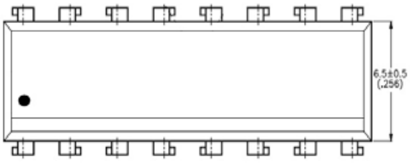


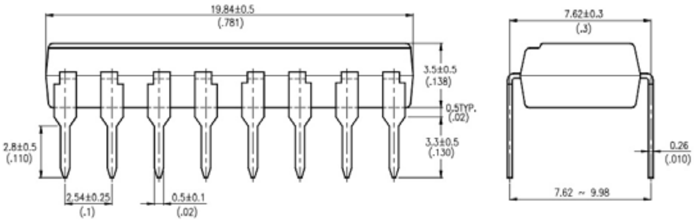
TLP621-2





TLP621-4





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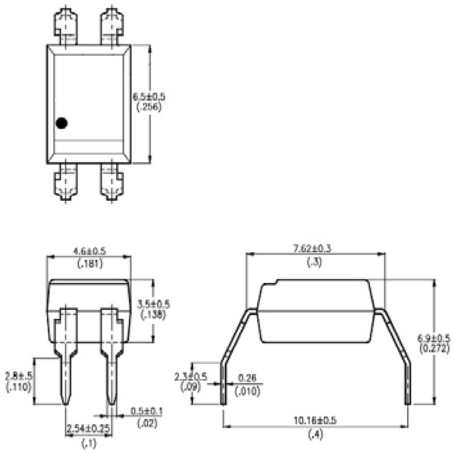
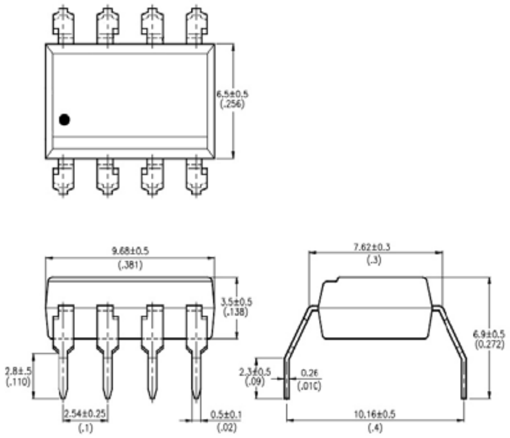
PACKAGE DIMENSIONS in mm (inch)

G Form

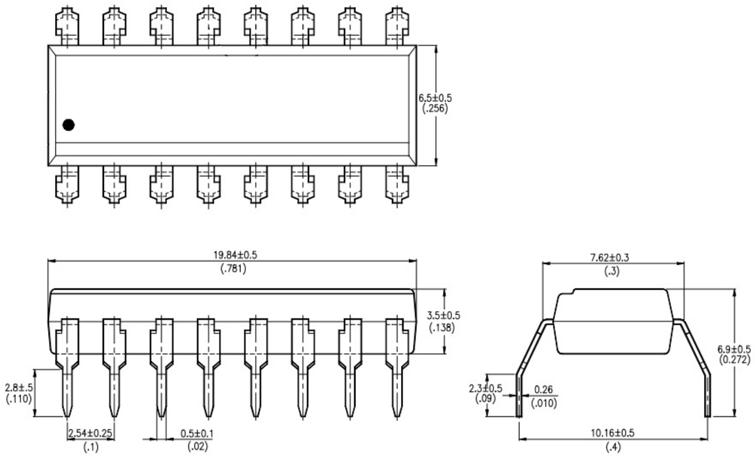
TLP621G



TLP621-2G



TLP621-4G



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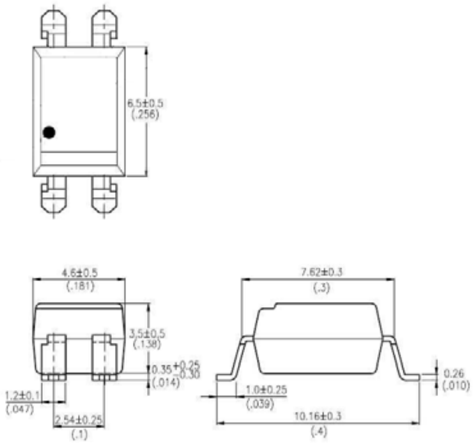
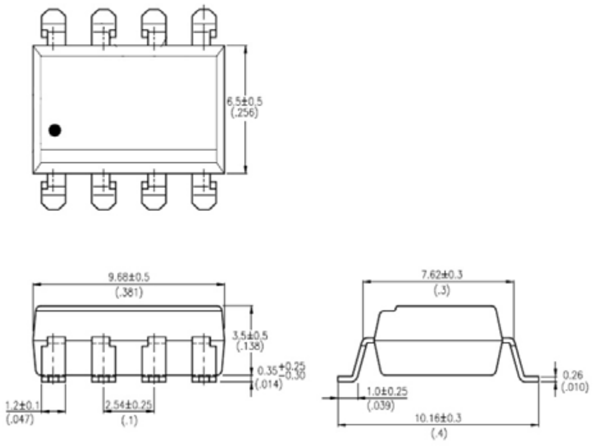
PACKAGE DIMENSIONS in mm (inch)

SMD

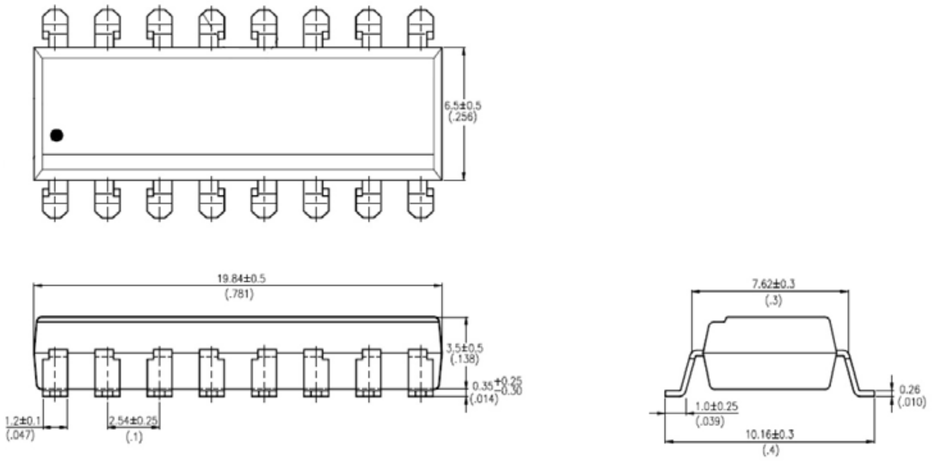
TLP621SM



TLP621-2SM



TLP621-4SM



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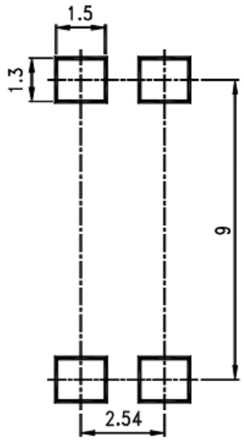
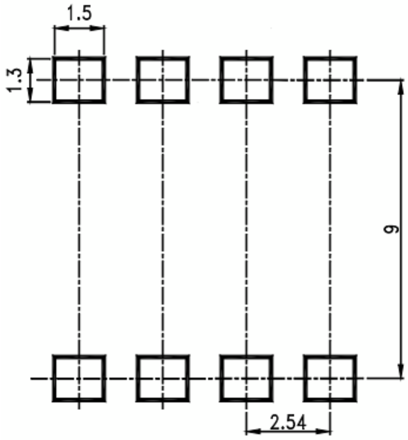
RECOMMENDED PAD LAYOUT FOR SMD (mm)

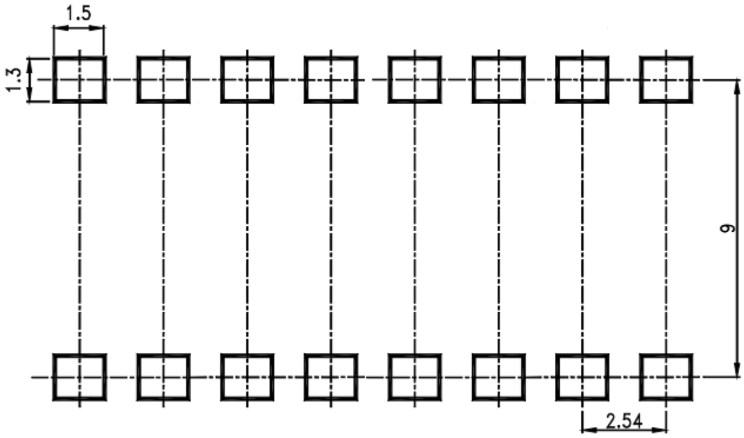
TLP621SM



TLP621-2SM



TLP621-4SM



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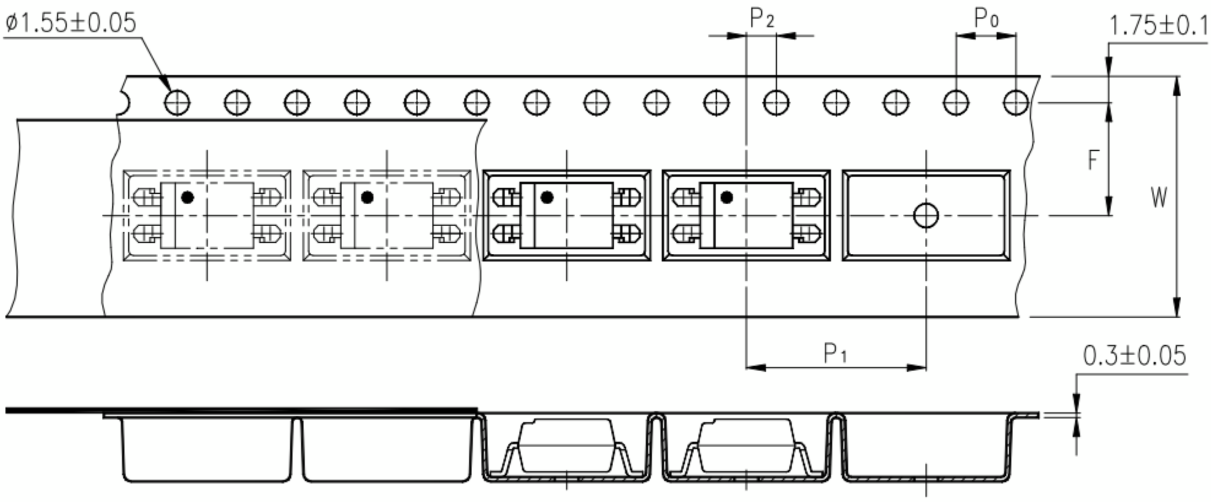
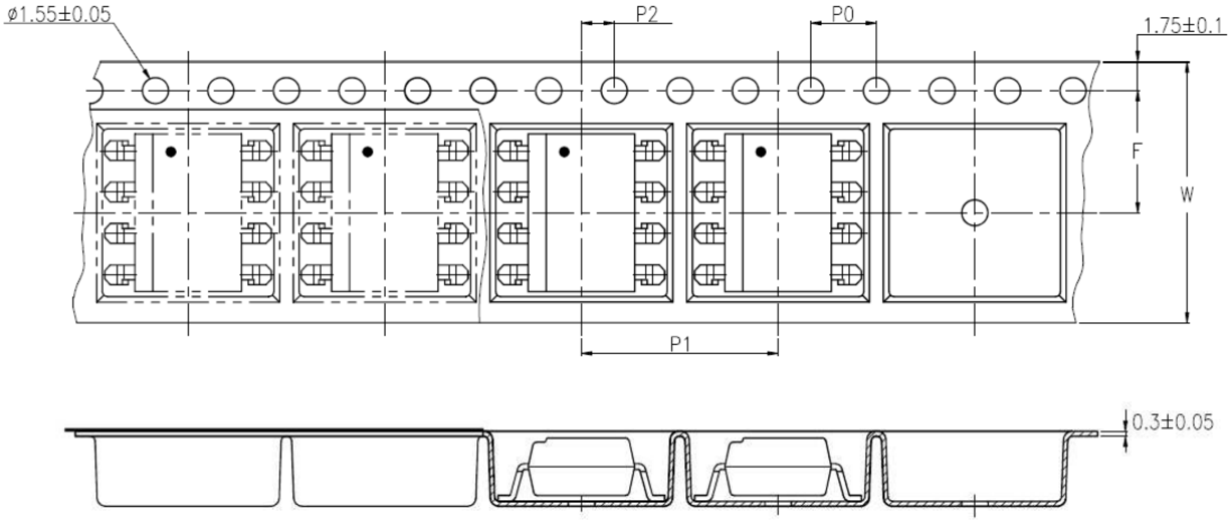
TAPE AND REEL PACKAGING



TLP621SMT&R



TLP621-2SMT&R

Description	Symbol	Dimensions in mm (inches)
Tape wide	W	16 ± 0.3 (.63)
Pitch of sprocket holes	P_0	4 ± 0.1 (.15)
Distance of compartment	F P_2	7.5 ± 0.1 (.295) 2 ± 0.1 (.079)
Distance of compartment to compartment	P_1	12 ± 0.1 (.472)

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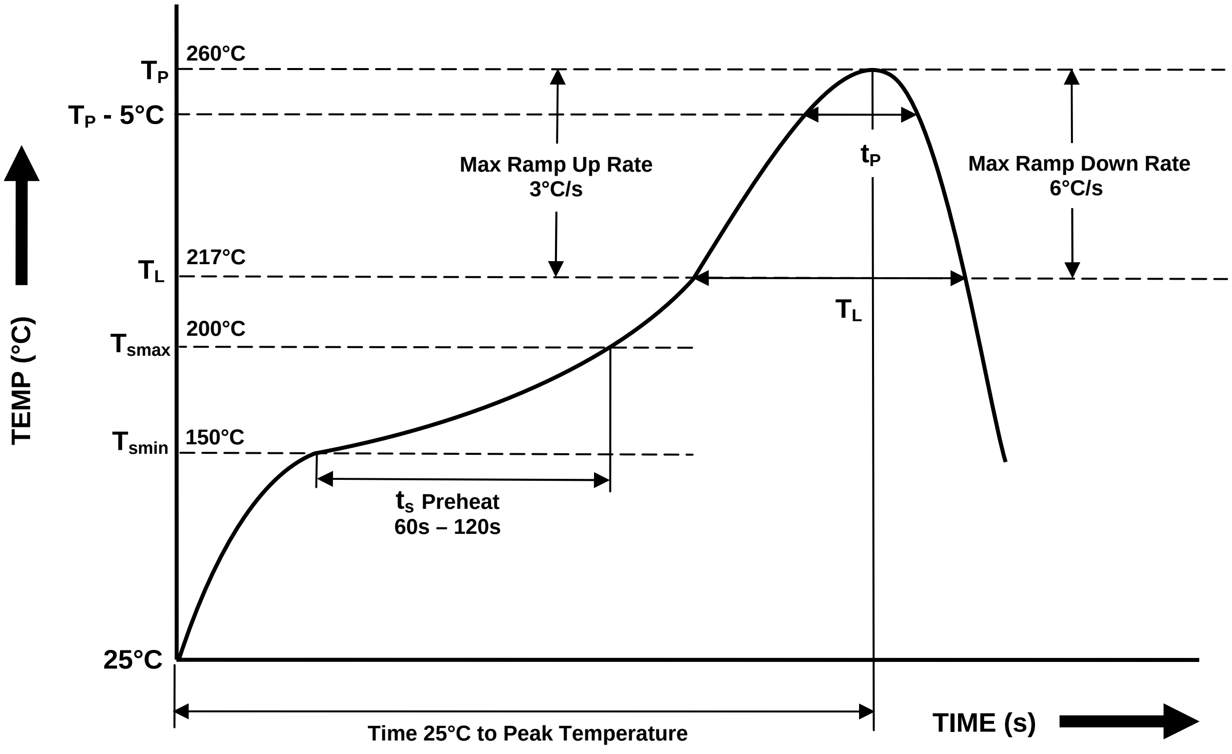
IR REFLOW SOLDERING TEMPERATURE PROFILE FOR SMD (One Time Reflow Soldering is Recommended)



Profile Details	Conditions
Preheat - Min Temperature (T_{SMIN}) - Max Temperature (T_{SMAX}) - Time T_{SMIN} to T_{SMAX} (t_s)	 150°C 200°C 60s - 120s
Soldering Zone - Peak Temperature (T_P) - Time at Peak Temperature - Liquidous Temperature (T_L) - Time within 5°C of Actual Peak Temperature (T_P – 5°C) - Time maintained above T_L (t_L) - Ramp Up Rate (T_L to T_P) - Ramp Down Rate (T_P to T_L)	 260°C 10s max 217°C 30s max 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T_{smax} to T_P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max

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- For equipment/application where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc., please contact our sales representatives.

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